

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10026	257/778-780,737-738,e23.021,e23.069.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 08:13
L2	89	(chip die ic (integrated adj circuit) (semiconductor near1 (element device component))) same passivation same ((conductive solder gold metal) near (bump ball)) same adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 08:20
L3	17	2 and ((bump ball) near3 (exposed exposing expose))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 08:21
L4	2388	(chip die ic (integrated adj circuit) (semiconductor near1 (element device component))) and passivation and ((conductive solder gold metal) near (bump ball)) and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 08:20
L5	350	4 and ((bump ball) near3 (exposed exposing expose))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 08:21
L6	25	4 and (((bump ball) near3 (exposed exposing expose)) with adhesive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/02 08:22